

# PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Tzu-Wei Chiu	10/29/2010
<b>RECEIVING PARTY DATA</b>	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	12938680
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ATTORNEY DOCKET NUMBER:	2010-659/24061.1552
NAME OF SUBMITTER:	David M. O'Dell
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OP \$40.00 12938680

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**PATENT**  
 REEL: 025657 FRAME: 0384

**ASSIGNMENT**

WHEREAS, I

Tzu-Wei Chiu                      of                      2Fi-1, No. 38, Sec. 1, Guangfu Rd.,  
Hsin Chu, Taiwan, R.O.C.

has invented certain improvements in

**SEAL RING STRUCTURE WITH POLYIMIDE LAYER ADHESION**

for which I have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and  
filed on 11-03-2010 and assigned application number 12/938,680; and

WHEREAS, I authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Docket No.: 2010-0659 / 24061.1552  
Customer No.: 42717

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Inventor Name: Tzu-Wei Chiu

Residence Address: 2F-1, No. 38, Sec. 1, Guangfu Rd.,  
Hsin Chu, Taiwan, R.O.C.

Dated: 2010.10.27

Tzu-Wei Chiu  
Inventor Signature

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